

N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)			
100	0.035 at V _{GS} = 10 V	50 ^a			

FEATURES

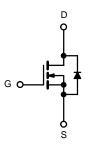
- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R_g Tested



APPLICATIONS

• Isolated DC/DC Converters





N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	S T _C = 25 °C, unless oth	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage	V _{GS}	± 20	v	
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 25 °C	I-	50 ^a	
Continuous Diam Current (1) = 175 C)	T _C = 125 °C	I _D	39 ^a	
Pulsed Drain Current		I _{DM}	150	А
Avalanche Current L = 0.1 mH		I _{AS}	39	
Single Pulse Avalanche Energy ^b	L = 0.111111	E _{AS}	61	mJ
Mariana Barra Birainata b	T _C = 25 °C	В	375 ^c	10/
Maximum Power Dissipation ^b	T _A = 25 °C ^d	P _D	3.75	W
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount	R_{thJA}	40	°C/W		
Junction-to-Case (Drain)		R_{thJC}	0.4	C/VV		

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. See SOA curve for voltage derating.
- d. When Mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{DS} = 0 \text{ V, } I_{D} = 250 \mu\text{A}$				V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = 100 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C			50	, I	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.035			
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.063		Ω	
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.084			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b							
Input Capacitance	C _{iss}			5100		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		480			
Reverse Transfer Capacitance	C _{rss}			210			
Total Gate Charge ^c	Qg			90			
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 65 \text{ A}$		23		nC	
Gate-Drain Charge ^c	Q_{gd}			34			
Gate Resistance	R_g		0.5	1.7	3.3	Ω	
Turn-On Delay Time ^c	t _{d(on)}			24	35		
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_{L} = 1.5 \Omega$		220	330	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 65 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		45	70		
Fall Time ^c	t _f			200	300		
Source-Drain Diode Ratings and Cha	aracteristics 7	C _C = 25 °C ^b					
Continuous Current	Is			50		۸	
Pulsed Current	I _{SM}			150		A	
Forward Voltage ^a	V _{SD}	I _F = 65 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			130	200	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 50 A, di/dt = 100 A/μs		8	12	Α	
Reverse Recovery Charge	Q _{rr}			0.52	1.2	μC	

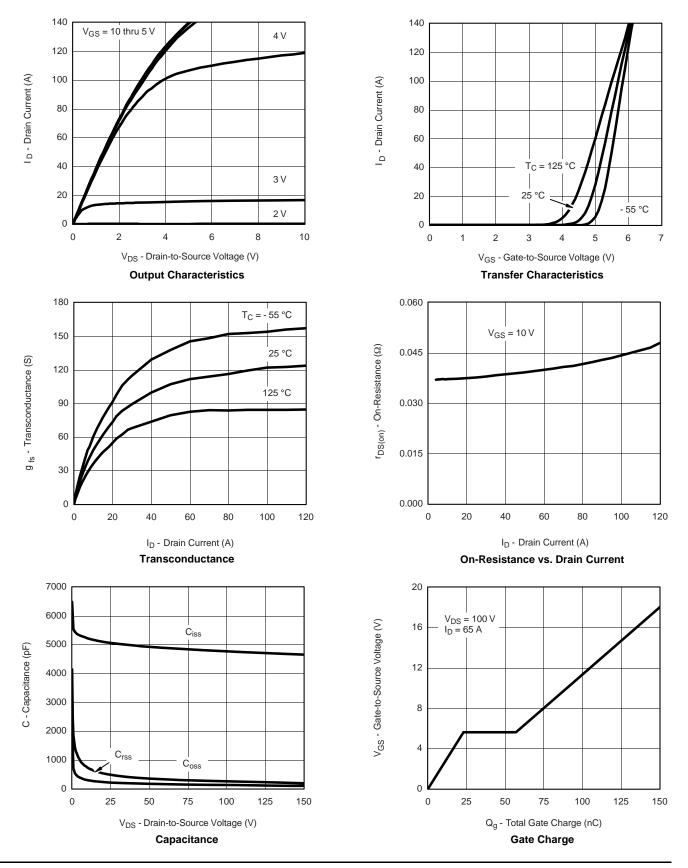
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

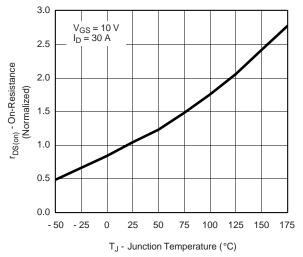


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

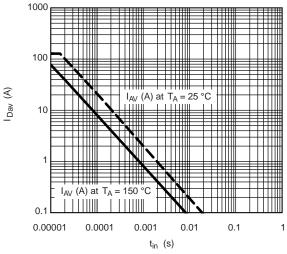




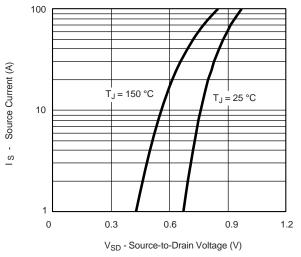
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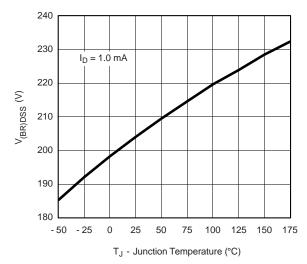
On-Resistance vs. Junction Temperature



Avalanche Current vs. Time



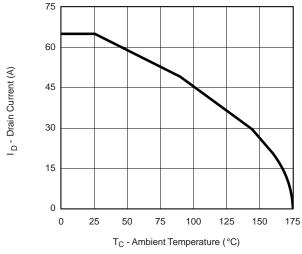
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature

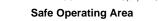


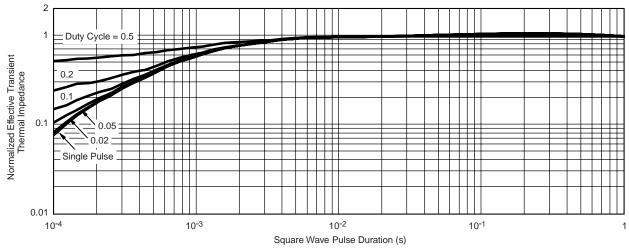
THERMAL RATINGS



1000 r_{DS(on)} Limited 10 µs 100 I_D - Drain Current (A) 10 1 ms T_C = 25 °C Single Pulse 10 ms 100 ms DC 0.1 0.1 100 1000 10 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $r_{DS(on)}$ is specified

Maximum Avalanche and Drain Current vs. Case Temperature

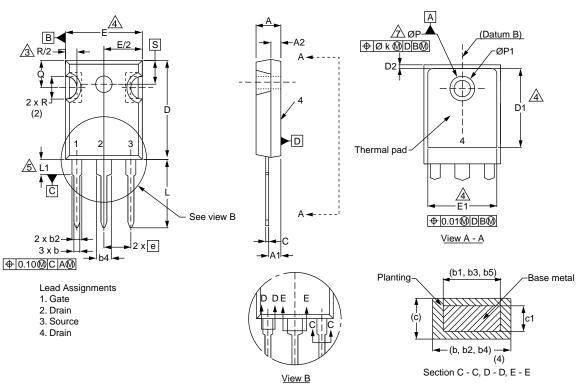




Normalized Thermal Transient Impedance, Junction-to-Case



TO-247AC



	MILLIM	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.58	5.31	0.180	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.17	2.49	0.046	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.53	2.39	0.060	0.094	
b3	1.65	2.37	0.065	0.093	
b4	2.42	3.43	0.095	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.86	0.015	0.034	
c1	0.38	0.76	0.015	0.030	
D	19.71	20.82	0.776	0.820	
D1	13.08	-	0.515	-	

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D2	0.51	1.30	0.020	0.051
E	15.29	15.87	0.602	0.625
E1	13.72	-	0.540	-
е	5.46 BSC		0.215 BSC	
Øk	0.2	254	0.0)10
L	14.20	16.25	0.559	0.640
L1	3.71	4.29	0.146	0.169
N	7.62 BSC		0.300 BSC	
ØΡ	3.51	3.66	0.138	0.144
Ø P1	-	7.39	-	0.291
Q	5.31	5.69	0.209	0.224
R	4.52	5.49	0.178	0.216
S	5.51 BSC		0.217 BSC	



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